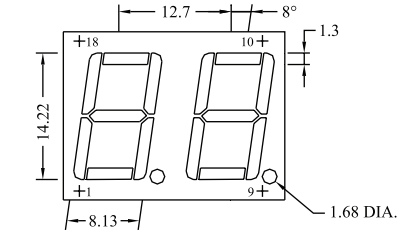
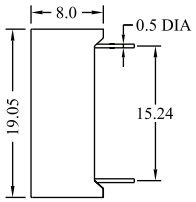
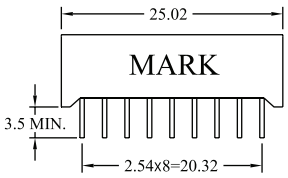
0.56" Dual Digit Display

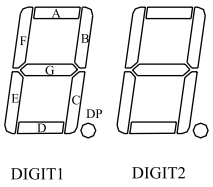
RoHS Compliant

Package Dimensions:

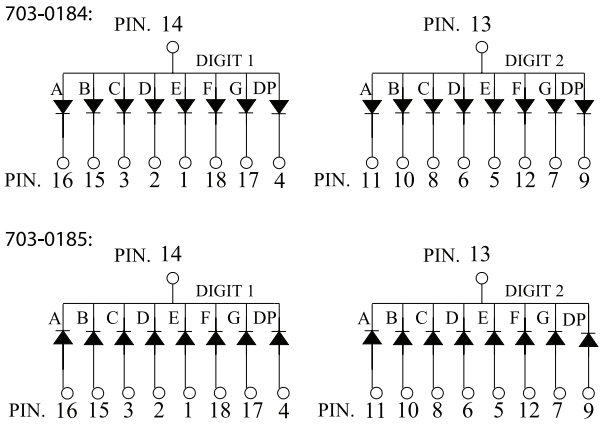








Internal Circuit Diagram:



All dimensions are in mm
Tolerance: ±0.25mm
The slope angle of any PIN may be ±5° max

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation - Pre Segment	P_D	72	mW
Pulse Current (1/10 Duty Cycle, 0.1ms Pulse Width) - Per Chip	I_{FP}	100	mA
Forward Current - Per Chip	I_F	30	mA
Reverse (Leakage) Current - Per Chip	Ir	100	µA
Reverse Voltage - Per Chip	V_R	5	V
Operating Temperature Range	Topr.	-25 to +85	°C
Storage Temperature Range	Tstg.	-40 to +100	°C
Soldering Temperature	Tsol.	Dip Soldering: 260°C for 5sec. Hand Soldering: 350°C for 3 sec.	

Electrical & Optical Characteristics:

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity - Per Segment	Iv	If=10mA / seg.	1.15	3.3		mcd
Forward Voltage	Vf	If=20mA / seg.		2.1	2.6	V
Peak Wavelength	λp	If=20mA / seg.		635		nm
Dominant Wavelength	λd	If=20mA / seg.		626		nm
Reverse Current - Per Chip (Leakage Current - Per Chip)	Ir	Vr=5V			100	μA
Spectrum Line Halfwidth	Δλ	If=20mA / seg.		35		deg
Response Time	T			250		nm

Note: Customer's special requirements are also welcome.

Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)

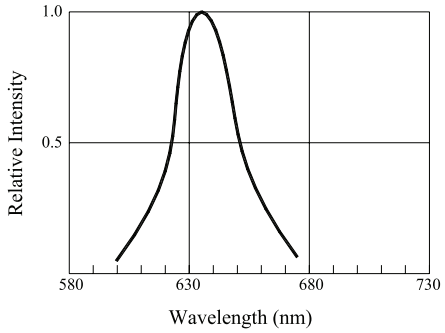


Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

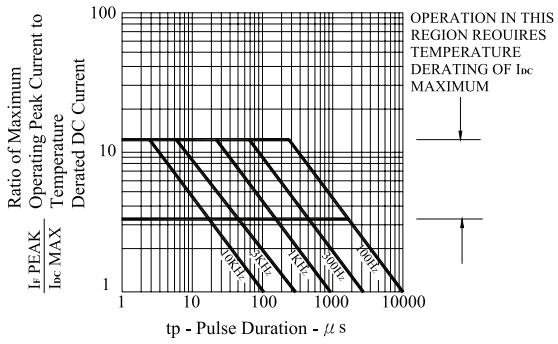


Fig.2 MAXIMUM TOLERABLE PEAK CURRENT VS. PULSE DURATION

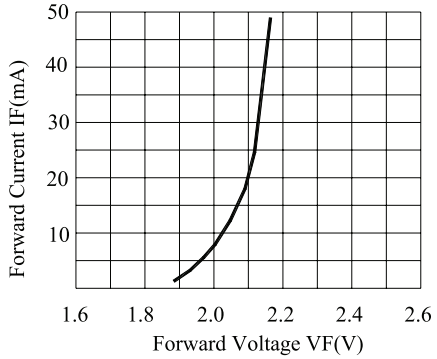


Fig .3 FORWARD CURRENT VS. FORWARD VOLTAGE PER CHIP

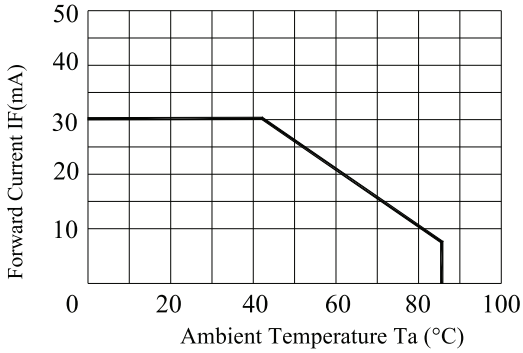


Fig.4 FORWARD CURRENT VS. DERATING CURVE

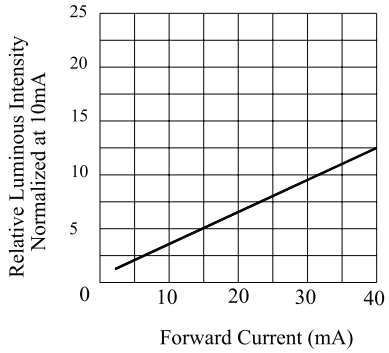


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

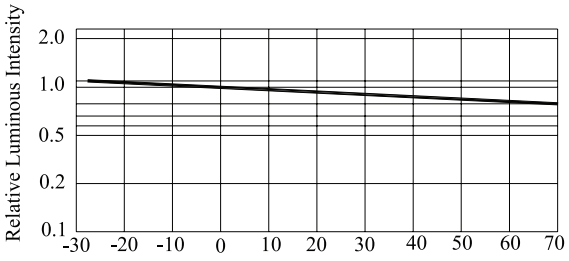


Fig.6 LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

Part Number Table

LED Chip		Face Colour		Part Number
Material	Emitting Colour	Surface	Segments	
GaAsP / GaP	Orange	Grey	White	703-0184
GaAsP / GaP	Orange	Grey	White	703-0185